# 157 Series — Standard Nano<sup>2®</sup> Fuse and Clip Assembly





#### **Agency Approvals**

Agency	Agency File Number	Ampere Range
c <b>FL</b> °us	E14721	0.062A - 10A
PS	NBK030205-E10480A NBK030205-E10480B NBK101105-E184655	1A - 1.6A 2A - 5A 6.3A - 10A

#### **Electrical Characteristics for Series**

% of Ampere Rating	Opening Time at 25°C	
100%	4 hours Minimum	
200%	5 secs. Maximum	

#### **Description**

The 157 Series – Standard Nano Fuse/Clip assembly is a small, square, very fast-acting surface mount fuse that is assembled in surface mountable fuse clips. The fuse clip and pre-installed fuse combination can be automatically placed in PC Board in one efficient manufacturing operation. It permits quick and easy replacement of fuses without performing desoldering process, even in the field and without exposing the PC Board to detrimental effects of rework solder heat.

#### **Features**

- Surface Mountable
- Very Fast-Acting Fuse
- Fully compatible with RoHS/Pb-Free solder alloys and higher temperature profiles associated with leadfree
- assembly.
- Easily replaceable on PC Board (Field Replaceable)
- RoHS compliant and Halogen Free
- Available in ratings of 0.062 ~ 10 Amperes.

#### **Applications**

- Instrumentation
- Telecommunications
- Base Stations

### **Electrical Specifications by Item**

Ampere	Amp	Max Voltage	Interrupting	rupting Fuse Nominal Cold		Nominal	Agency Approvals	
Rating (A)	Code	Rating (V)	Rating (A)	Furnished	Resistance (Ohms)	Melting I²t (A²sec)	c <b>FL</b> °us	PS E
0.062	0.062	125		451.062	5.5372	0.00019	X	-
0.08	0.08	125		451.08	4.0500	0.00033	X	-
0.1	0.1	125		451.1	3.1000	0.00138	X	-
0.125	0.125	125		451.125	1.7059	0.00286	X	-
0.16	0.16	125		453.16	1.2157	0.0048	X	-
0.2	0.2	125		453.2	1.3971	0.00652	X	-
0.25	0.25	125		453.25	1.0496	0.01126	X	-
0.315	0.315	125		453.315	0.3881	0.0311	X	-
0.375	0.375	125		453.375	0.4518	0.0442	X	-
0.4	0.4	125		453.4	0.4212	0.0551	X	-
0.5	0.5	125		453.5	0.3031	0.0824	X	-
0.63	0.63	125		453.63	0.2012	0.1381	X	-
0.75	0.75	125	FOA @ 10F \/ACA/DC	453.75	0.1437	0.2143	X	-
0.8	0.8	125	50A @ 125 VAC/VDC	453.8	0.1348	0.2654	X	-
1.0	1.0	125	300A @ 32 VDC	453001.0	0.0776	0.6029	X	X
1.25	1.25	125	300A @ 32 VDC	4531.25	0.078	0.664	X	X
1.5	1.5	125		45301.5	0.0634	0.853	X	X
1.6	1.6	125		45301.6	0.0580	1.06	X	X
2.0	2.0	125		453002.0	0.0373	0.53	X	X
2.5	2.5	125		45302.5	0.0288	1.029	X	X
3.0	3.0	125		453003.0	0.0229	1.65	X	X
3.15	3.15	125		4533.15	0.0215	1.92	X	X
3.5	3.5	125		45303.5	0.0203	2.469	X	X
4.0	4.0	125		453004.0	0.0163	3.152	X	X
5.0	5.0	125		453005.0	0.0127	5.566	X	Χ
6.3	6.3	125		45306.3	0.0098	9.17	X	Χ
7.0	7.0	125		453007.0	0.0092	10.32	X	Χ
8.0	8.0	125		453008.0	0.0079	20.23	X	Χ
10.0	10.0	125	35A @ 125 VAC / 50A @125 VDC 300A @ 32VDC	453010.0	0.0058	26.46	×	X

<sup>1.</sup> Cold resistance measured at less than 10% of rated current at 23°C.

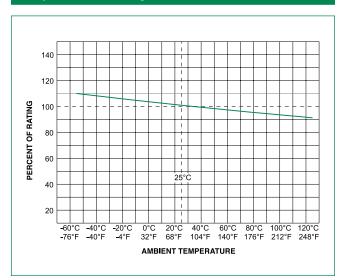
4. Have special electrical characteristic needs? Contact Littelfuse to learn more about application specific options.

<sup>2.</sup> Pt values stated for 8ms opening time.

<sup>3.</sup> Agency Approval Table Key: X=Approved or Certified, P=Pending and Blank=Not Approved



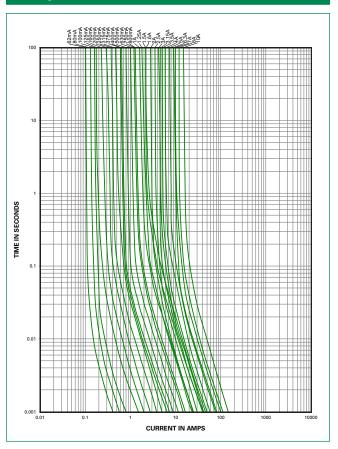
#### **Temperature Re-rating Curve**



#### Note:

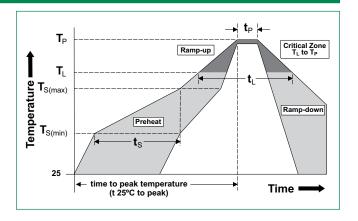
1. Rerating depicted in this curve is in addition to the standard derating of 25% for continuous operation.

#### **Average Time Current Curves**



### **Soldering Parameters**

Reflow Cond	Pb – Free assembly	
Pre Heat	-Temperature Min (T <sub>s(min)</sub> )	150°C
	-Temperature Max (T <sub>s(max)</sub> )	200°C
	-Time (Min to Max) (t <sub>s</sub> )	60 – 180 secs
Average ram	5°C/second max.	
T <sub>S(max)</sub> to T <sub>L</sub> - Ramp-up Rate		5°C/second max.
Reflow	-Temperature (T <sub>L</sub> ) (Liquidus)	217°C
	-Temperature (t <sub>L</sub> )	60 – 150 seconds
Peak Temper	260+0/-5 °C	
Time within	20 – 40 seconds	
Ramp-down	5°C/second max.	
Time 25°C to	8 minutes max.	
Do not exce	260°C	



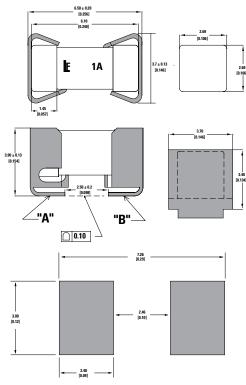
# **Surface Mount Fuses**

#### **Product Characteristics**

Materials	Materials  Body: Ceramic Cap: For 0.062A ~ 0.125A – Au plated Brass For 0.20 ~ 10A – Silver plated Brass Clip Plating: Matte Tin	
<b>Product Marking</b>	Body: Brand Logo, Current Rating	
Clip Retention	Force applied at fuse center, perpendicular to the long axis (@ 0.75 lbs. MIN)	
Solderability	MILSTD-202, Method 208 / IPC/ EIA / JEDEC J-STD-002, Test Condition A	
Humidity Test	MIL -STD-202, Method 103 @ 85°C / 85%RH, 1000 hours	
Resistance to Solvents	MIL-STD-202, Method 215 (3 solvent types)	

Operating Temperature	-55°C to 125°C with proper derating
	MIL-STD-202, Method 107,
Thermal Shock	Test Condition B
	(5 cycles -65°C to +125°C)
Vibration	MIL-STD-202, Method 201
vibration	(10-55 Hz)
Moisture Resistance	MIL-STD-202, Method 106,
Worsture Resistance	10 cycles
	MIL-STD-202, Method 101,
Salt Spray/ Atmosphere	Test Condition B (48 hrs.),
	5% NaCl in De-ionized Water
	MIL-STD-202, Method 213,
Shock	Test Condition I (100 G's peak for 6
	milliseconds)

#### **Dimensions**



## **Additional Information**

**Part Numbering System** 

**Series** 

**Amp Code** 

**Packaging** 

Packaging

Option

Tape and Reel

0157 001. D R

Packaging Specification

Surface Mount







**Packing Option** R = Tape and Reel

Quantity &

Packaging Code

DR

**Quantity Code** D = 1500 pcs

Quantity

1500

#### **PCB Recommendation for Thermal Management**

- 1. Minimum Copper Layer Thickness = 100um
- 2. Minimum Copper Trace Width = 10mm

Alternate methods of thermal management may be used. In such cases, under normal operations, the maximum temperature of the fuse body should not exceed  $80^{\circ}$ C in a  $25^{\circ}$ C ambient environment.